VERSAL[™] PREMIUM SERIES VPK180 EVALUATION KIT

OVERVIEW

MD2

The VPK180 Evaluation Kit features the Versal[™] Premium series VP1802 device, which offers a powerful combination of over 7 M logic cells, 112 G PAM4 transceivers, and hardened, power-optimized cores for multi-terabit interfacing.

The kit comes with a breadth of connectivity options, development tools, and example designs to accelerate prototyping of demanding compute and networking systems across multiple markets.

HIGHLIGHTS

Versal Premium Series Capabilities

- High I/O bandwidth and logic density
- 112 G PAM4 transceivers
- 600 G Ethernet (DCMAC) cores, supporting 100-400 GbE standards
- 100 G Multirate Ethernet (MRMAC) cores, supporting 10-100 GbE standards
- 400 G High-Speed Cryptographic (HSC) engines

Breadth of Onboard Connectivity Options

- SFP-DD (4), QSFP-DD (6), and OSFP (1) connectors for high-speed data communication
- FPGA Mezzanine Card (FMC+) connector with 68 user-defined signals and 8 GTYPs
- 12 GB (6x 2 GB, 32-bit), 192-bit LPDDR4 component @ 4266 Mbps memory
- Micro SD card interface

Development Tools and Enhanced Debug Methodology

- Co-optimized with a Vivado[™] ML design suite voucher and the Vitis[™] unified software platform
- Shipped with pre-built boot images



TARGET APPLICATIONS

WIRED COMMUNICATION

- Data Center Interconnect
- Metro Core Transport
- Security Appliances

DATA CENTER

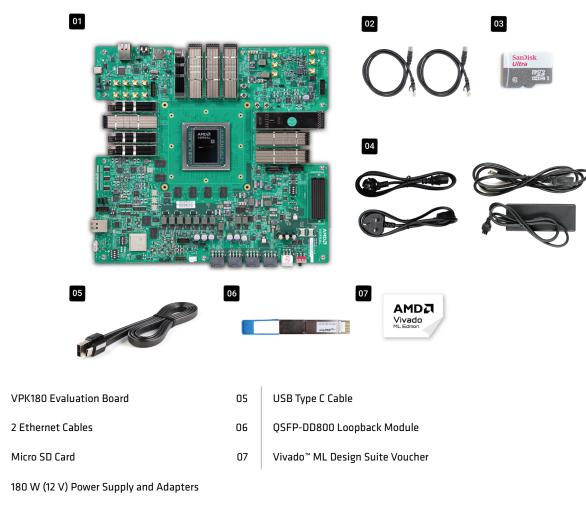
- Recommendation Systems
- Search Engines
- Video Analytics

TEST AND MEASUREMENT

- Network Testers
- PCIe[®] Protocol Analyzers
- RF/Microwave Instrumentation

AEROSPACE AND DEFENSE

- Avionics
- Digital Adaptive Radar
- Secure Communications



NEXT STEPS

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02

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• For more information, documents, and reference designs, or to purchase, visit www,amd.com/vpk180.

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